

# Specification of Thermoelectric Module

## TEHC1-08320P

### Description

The 83 couples, 44 mm × 38/42 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 74°C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

### Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

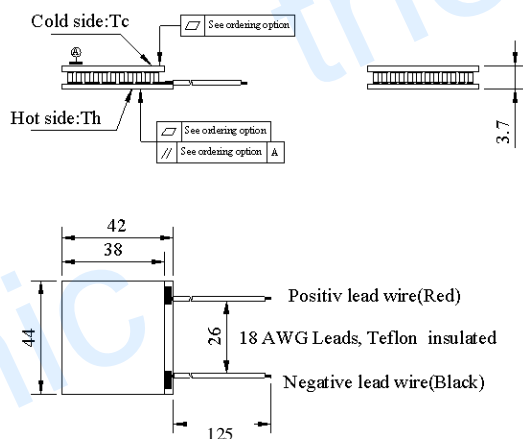
### Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

### Performance Specification Sheet

Th(°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>
DT <sub>max</sub> (°C)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U <sub>max</sub> (Voltage)	10.9	11.8	Voltage applied to the module at DT <sub>max</sub>
I <sub>max</sub> (amps)	19.6	19.6	DC current through the modules at DT <sub>max</sub>
Q <sub>Cmax</sub> (Watts)	136.8	149.3	Cooling capacity at cold side of the module under DT=0 °C
AC resistance(ohms)	0.44	0.46	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

### Geometric Characteristics Dimensions in millimeters



### Ordering Option

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:3.7±0.1	0:0.05/0.05	125±1/Specify
TF	1:3.7±0.05	1:0.025/0.025	125±1/Specify
TF	2:3.7±0.025	2:0.015/0.015	125±1/Specify

Eg. TF01: Thickness 3.7±0.1(mm) and Flatness 0.025/0.025(mm)

### Manufacturing Options

#### A. Solder:

1. T100: BiSn (Melting Point=138°C)
2. T200: CuSn (Melting Point= 227 °C)

#### B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant
4. Customer specify sealing

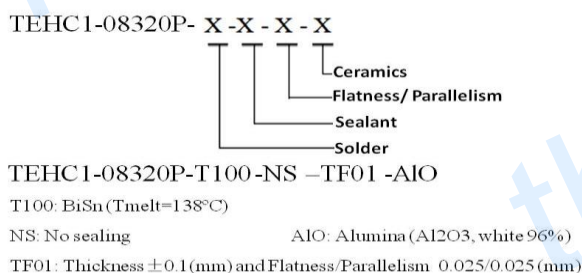
#### C. Ceramics:

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)(AIO)
2. Aluminum Nitride (AlN)

#### D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized (Copper-Nickel plating)

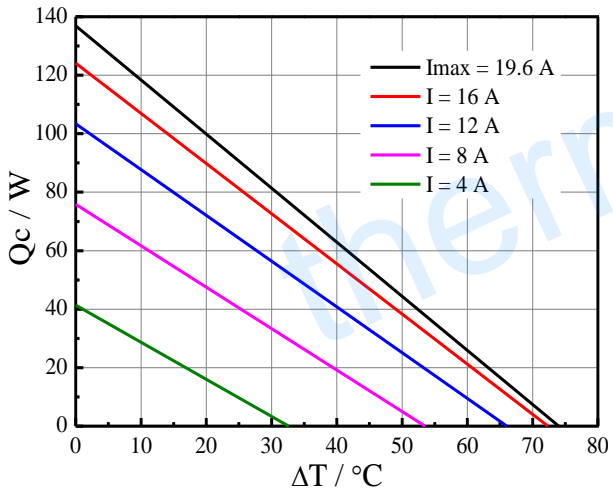
### Naming for the Module



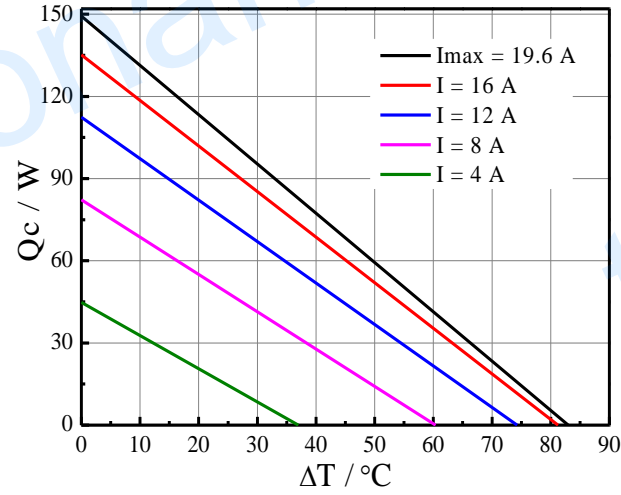
**Specification of Thermoelectric Module**

**TEHC1-08320P**

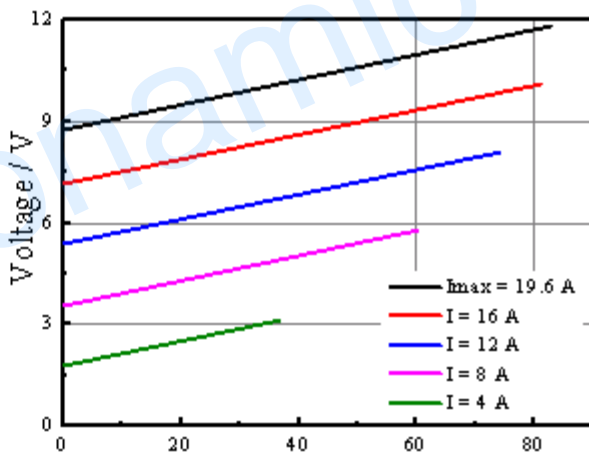
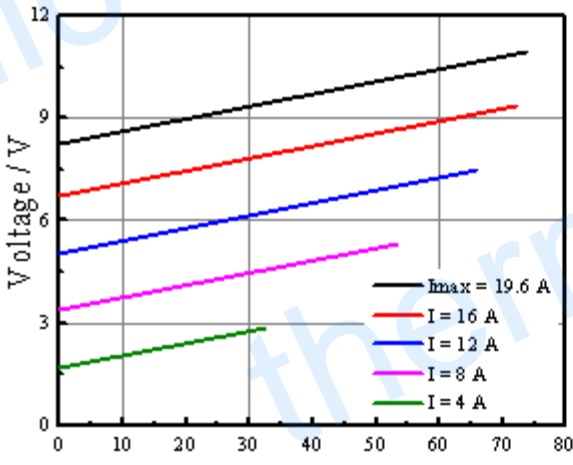
**Performance Curves at Th=27 °C**



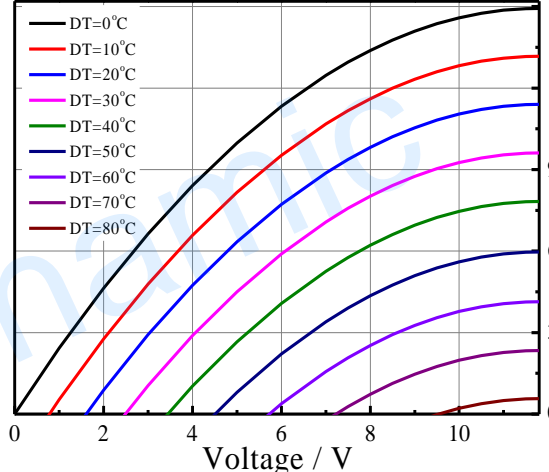
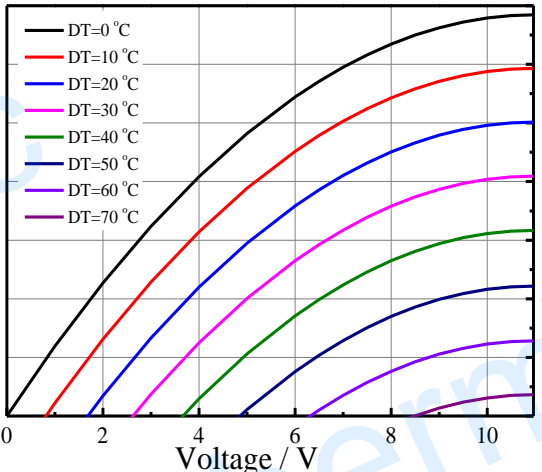
**Performance Curves at Th=50 °C**



Standard Performance Graph  $Q_c = f(\Delta T)$



Standard Performance Graph  $V = f(\Delta T)$

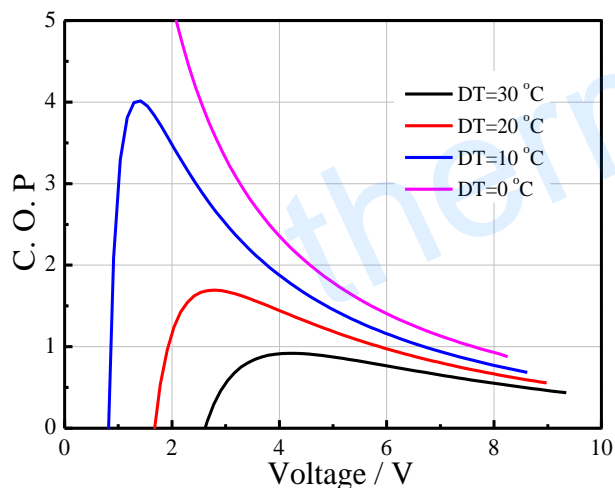


Standard Performance Graph  $Q_c = f(V)$

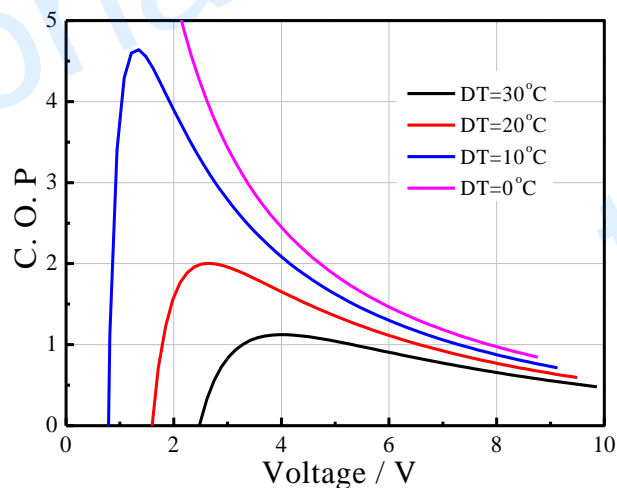
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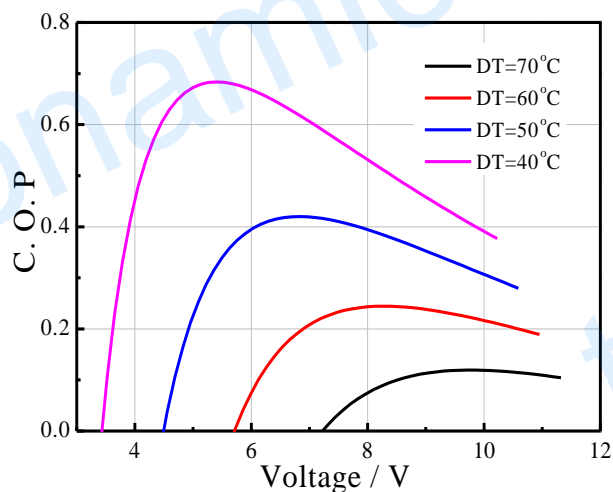
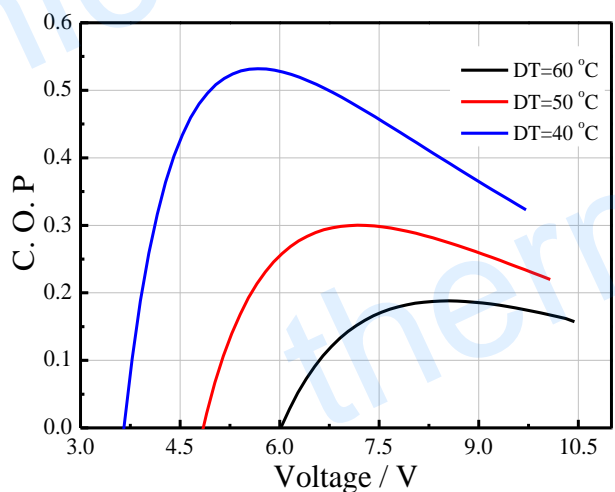
### Performance Curves at $T_h=27\text{ }^\circ\text{C}$



### Performance Curves at $T_h=50\text{ }^\circ\text{C}$



Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power  $Q_c$ /Input power ( $V \times I$ ).

### Operation Cautions

- Cold side of the module stucked on the object being cooled
- Hot side of the module mounted on a heat radiator
- Operation or storage module below 100 °C
- Operation below  $I_{max}$  or  $V_{max}$
- Work under DC